504523041 08/28/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4569747

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
I-Fan Chang	08/24/2017
Yen-Liang Wu	08/24/2017
Wen-Tsung Chang	08/24/2017
Jui-Ming Yang	08/24/2017
Jie-Ning Yang	08/24/2017
Chi-Ju Lee	08/24/2017
Chun-Ting Chiang	08/24/2017
Bo-Yu Su	08/24/2017
Chih-Wei Lin	08/24/2017
Dien-Yang Lu	08/24/2017

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15688852

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER: NAUP3103USA

NAME OF SUBMITTER: SIBYL YU

PATENT 504523041 REEL: 043427 FRAME: 0666

SIGNATURE:	/SIBYL YU/
DATE SIGNED:	08/28/2017
Total Attachments: 20	
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PATENT REEL: 043427 FRAME: 0667

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	eby declare that:		
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☐ PCT international application	on number	filed on	
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I believe that I am the original inven application.	tor or an original joint inventor of a	a claimed invention in the	
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(referred to as "ASSIGNEE"below) t acknowledged, andfor other good a	to I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of which is hereby	
hereby sell, assign and transfer to the entire right, title and interest in a nvention as above-identified applica nvention by the above application of substitutes, or extensions thereof, a	and to any and all improvements wation and, in and to, all Letters Pater any continuations, continuation-	hich are disclosed in the tent to be obtained for said in-part, divisions, renewals	
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further covenant that ASSIGNEE wand documents relating to said inversions, and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	
representatives any and all papers, maintain, issue and enforce said ap equivalents thereof which may be no N WITNESS WHEREOF, I have he	plication, said invention and said tecessary or desirable to carry out	Letters Patent and said	ıg)
Note: An application data sheet (PT nventive entity, must accompany th	O/SB/14 or equivalent), including is form. Use this form for <u>each</u> ad	naming the entire ditional inventor.	

Page 1 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: I-Fan Chang

Date: AUG 2 4 2017

Signature: I-Fan Chang

Page 2 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Title of Invention:

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(referred to as "ASSIGNEE"below) t acknowledged, andfor other good ar	o I of the sum of One E nd valuable considerati	ollar (\$ 1.00), the	receipt of wh	ich is hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified application of the above application of substitutes, or extensions thereof, and	nd to any and all impro ation and, in and to, all r any continuations, co	vements which are Letters Patent to b ntinuation-in-part,	e disclosed in le obtained fo divisions, ren	the r said ewals,
I hereby covenant that no assignme entered into which would conflict wit	nt, sale, agreement or hithis assignment;	encumbrance has	been or will b	e made or
I further covenant that ASSIGNEE wand documents relating to said inverse known and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters F estify as to the same in	Patent and legal ed any interference, I	uivalents as litigation proc	mav be
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention acessary or desirable to	and said Letters For carry out the pro	Patent and sa poses thereof	iid f. (Date of signing)
Note: An application data sheet (PT inventive entity, must accompany th	O/SB/14 or equivalent) is form. Use this form f	, including naming or each additional	the entire inventor.	

Page 3 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yen-Liang Wu

Date:

AUG 2 4 2017

Signature:

You - Liam

hu

Page 4 of 20

NPO#NAU-P3103-USA:0

CUST#UMCD-2017-0272

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbr h this assignment;	rance has	been or will be mad	e or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent are estify as to the same in any inte	nd legal eq rference, li	uivalents as may be itigation proceeding	Э
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	olication, said invention and said ecessary or desirable to carry o	d Letters F	Patent and said poses thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi	O/SB/14 or equivalent), includir s form. Use this form for each a	ng naming additional i	the entire	

5 of Page 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Wen-Tsung Chang Date: AUG 2 4 2017

signature: Wen-Tsung Chang

Page 6 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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I hereby covenant that no assignmentered into which would conflict with	nt, sale, agreement or encumbran h this assignment;	ce has been or will	be made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Patent and I estify as to the same in any interfe	legal equivalents as rence, litigation pro-	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and said Lecessary or desirable to carry out	etters Patent and s	of.
Note: An application data sheet (PT0 inventive entity, must accompany thi			

Page 7 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Inventor: Jui-Ming Yang

Date: AUG 2 4 2017

Signature: Jui-Ming Yang

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272 Page 8 of 20

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or wil	ll be made or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	plication, said invention and said L ecessary or desirable to carry out	_etters Patent and the proposes there	said
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 9 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Inventor: Jie-Ning Yang

Date: AUG 2 4 2017

Signature: JSE-Ning Yang

Page 10 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Title of Invention:

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Note: An application data sheet (PT0 inventive entity, must accompany this			

Page 11 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Chi-Ju Lee	Date:	AUG 2 4 2017	
Signature:	Chi-Ju Lee			

Page 12 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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Page 13 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chun-Ting Chiang	Date:	AUG 2 4 2017	
Signature:	Chun-Ting, Ch	iang		

Page 14 of 20

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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representatives any and all papers, maintain, issue and enforce said ap- equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention ecessary or desirable to	and said Letters F carry out the prop	Patent and said coses thereof.	e of signing)
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Page 15 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

Inventor:	Bo-Yu Su		Date:	AUG 2 4 2017	
Signature:		Bolh Su			_

LEGAL NAME OF INVENTOR(ASSIGNOR)

Page 16 of 20

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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Page 17 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chih-Wei Lin	Date;	AUG 2 4 2017	
Signature:	Chilv-Wei Low	,		

Page 18 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

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Page 19 of 20

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Dien-Yang Lu

Date: AUG 2 4 2017

Signature: Dicn - Yang Lu.

NPO#NAU-P3103-USA:0 CUST#UMCD-2017-0272

RECORDED: 08/28/2017

Page 20 of 20

F#NPO-P0002E-US1201 DSB0-106U017457

PATENT REEL: 043427 FRAME: 0687